

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	280	Mold\$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L2	94	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L3	614	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L4	4119	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L5	3516	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L6	3491	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L7	92	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L8	87	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03

L9	1639	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L10	280	Mold\$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L11	94	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L12	614	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L13	4119	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L14	3516	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L15	3491	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L16	92	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L17	87	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L18	1639	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03

L19	32	("4891687" "5929517" "5973389" "6020221" "6279758" "6284569" "6303985" "6326544" "6426565" "6440777" "6486562" "6517662" "6519843" "6584897" "6599365" "6724071").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L20	2	("4710419").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L21	2	("5650593").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L22	10591	spray\$3 near3 mold \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L23	302	L22 and semiconductor and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03
L24	280	Mold\$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/12 15:03

6/ 12/ 08 3:55:29 PM

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